

Applicant: Tadahiro OHMI et al  
Title: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND  
METHOD OF ETCHING AN INSULATING FILM  
Appl. No.: Unassigned  
Filing Date:  
Examiner: Unassigned  
Art Unit: Unassigned

**TRANSLATOR'S DECLARATION**

I, the below-named translator, certify that I am familiar with both the Japanese and the English language, that I have prepared the attached English translation of International Application No. PCT/JP2005/001513 and that the English translation is a true, faithful and exact translation of the corresponding Japanese language paper.

I further declare that all statements made in this declaration of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful, false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of legal decisions of any nature based on them.

August 3, 2006

Date

  
Name: Noriyasu Ikeda